Silicon Carbide Schottky Diode

650 V, 12 A

FFSH1265BDN-F085

Description

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size & cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 24.5 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery/No Forward Recovery
- AEC-Q101 Qualified
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

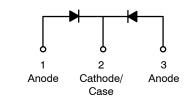
Applications

- Automotive HEV-EV Onboard Chargers
- Automotive HEV-EV DC-DC Converters

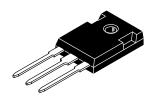


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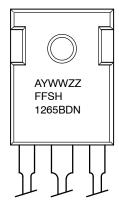


Schottky Diode



TO-247-3LD CASE 340CX

MARKING DIAGRAM



FFSH1265BDN = Specific Device Code

A = Assembly Location

Y = Year
WW = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

FFSH1265BDN-F085

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Value	Unit	
V_{RRM}	Peak Repetitive Reverse Voltage		650	V
E _{AS}	Single Pulse Avalanche Energy (Note 1)		24.5*	mJ
I _F	Continuous Rectified Forward Current @ T _C < 145°C		6*/12**	Α
	Continuous Rectified Forward Current @ T _C < 135°C		7.2*/14.4**	
I _{F, Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	510	Α
		T _C = 150°C, 10 μs	454	А
I _{F,SM}	Non-Repetitive Forward Surge Current $T_C = 25^{\circ}C$	Half-Sine Pulse, t _p = 8.3 ms	24	А
Ptot	Power Dissipation	T _C = 25°C	52	W
		T _C = 150°C	8.6	W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C
	TO247 Mounting Torque, M3 Screw		60	Ncm

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max	2.9*/1.5**	°C/W

^{*} Per Leg, ** Per Device

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted (per leg))

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V _F	Forward Voltage	I _F = 6 A, T _C = 25°C	-	1.38	1.7	V
		I _F = 6 A, T _C = 125°C	-	1.53	2.0	
		I _F = 6 A, T _C = 175°C	-	1.67	2.4	
I _R	Reverse Current	V _R = 650 V, T _C = 25°C	-	0.025	40	μΑ
		V _R = 650 V, T _C = 125°C	-	0.08	80	
		V _R = 650 V, T _C = 175°C	-	0.22	160	
Q_{C}	Total Capacitive Charge	V = 400 V	-	16	-	nC
С	Total Capacitance	V _R = 1 V, f = 100 kHz	-	259	-	pF
		V _R = 200 V, f = 100 kHz	-	29	_	
		V _R = 400 V, f = 100 kHz	-	22	_	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

PACKAGE MARKING AND ORDERING INFORMATION

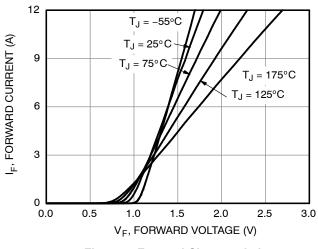
Part Number	Top Marking	Package	Shipping
FFSH1265BDN-F085	FFSH1265BDN	TO-247-3LD (Pb-Free / Halogen Free)	30 Units / Tube

^{*} Per Leg, ** Per Device

^{1.} E_{AS} of 24.5 mJ is based on starting T_J = 25°C, L = 0.5 mH, I_{AS} = 9.9 A, V = 50 V.

FFSH1265BDN-F085

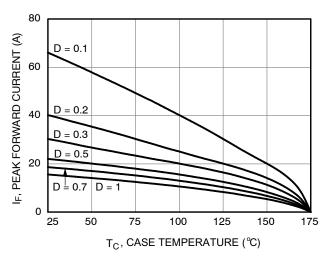
TYPICAL CHARACTERISTICS



10 -6 IR, REVERSE CURRENT (A) 10⁻⁷ $T_J = 175^{\circ}C$ $T_J = 125^{\circ}C$ 10 -8 T_J = 75°C $T_{J} = 25^{\circ}Q$ $T_J =$ 10 -9 100 0 300 400 600 650 V_R, REVERSE VOLTAGE (V)

Figure 1. Forward Characteristics

Figure 2. Reverse Characteristics



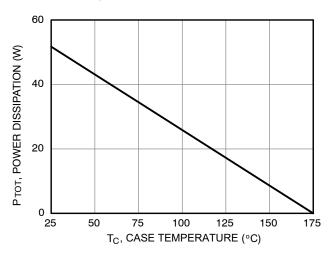
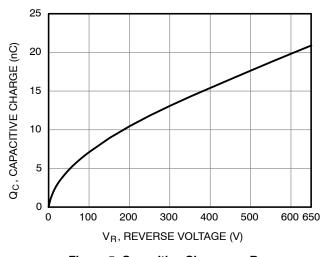


Figure 3. Current Derating

Figure 4. Power Derating



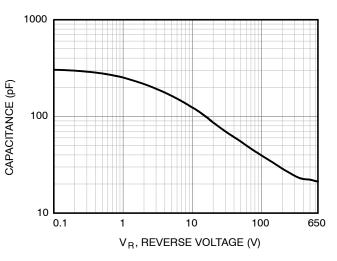


Figure 5. Capacitive Charge vs. Reverse Voltage

Figure 6. Capacitance vs. Reverse Voltage

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TYPICAL CHARACTERISTICS

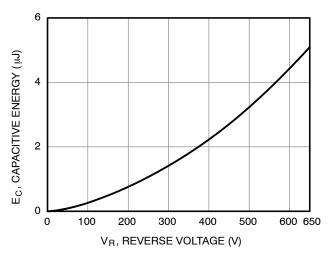


Figure 7. Capacitance Stored Energy

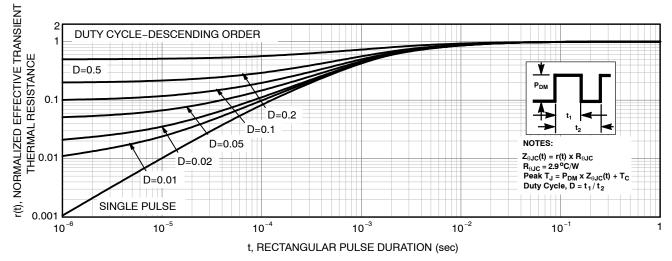


Figure 8. Junction-to-Case Transient Thermal Response

TEST CIRCUIT AND WAVEFORMS

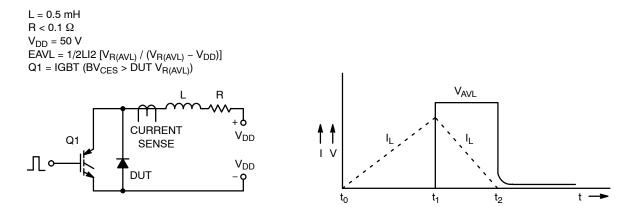
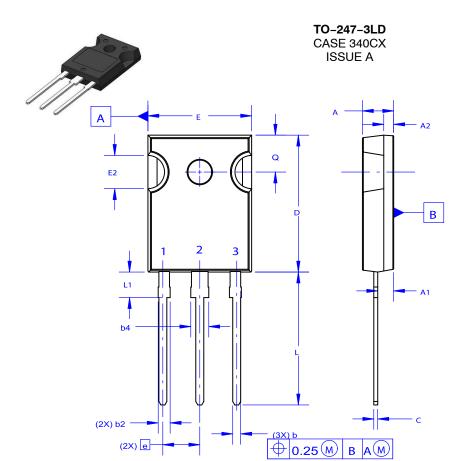
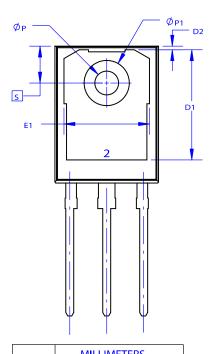


Figure 9. Unclamped Inductive Switching Test Circuit & Waveform



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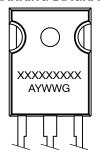


NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

 B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location

= Year WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " =", may or may not be present. Some products may not follow the Generic Marking.

DIM	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	4.58	4.70	4.82	
A 1	2.20	2.40	2.60	
A2	1.40	1.50	1.60	
D	20.32	20.57	20.82	
Е	15.37	15.62	15.87	
E2	4.96	5.08	5.20	
е	~	5.56	~	
L	19.75	20.00	20.25	
L1	3.69	3.81	3.93	
ØΡ	3.51	3.58	3.65	
Q	5.34	5.46	5.58	
S	5.34	5.46	5.58	
b	1.17	1.26	1.35	
b2	1.53	1.65	1.77	
b4	2.42	2.54	2.66	
С	0.51	0.61	0.71	
D1	13.08	~	~	
D2	0.51	0.93	1.35	
E1	12.81	~	~	
Ø P 1	6.60	6.80	7.00	

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